

FEATURES

- Oversampled successive approximation (SAR) architecture**
- High performance ac and dc accuracy, low power 115.5 dB typical dynamic range, 32 kHz output data rate (ODR)**
- 112 dB typical total harmonic distortion (THD)**
- Exceptionally low power**
- 8.5 mW, 32 kHz ODR**
- High dc accuracy**
- 24 bits, no missing codes (NMC)**
- Integral nonlinearity (INL): ±6 ppm (typical), ±15 ppm (maximum)**
- Low temperature drift**
- Zero error drift: 15 nV/°C typical**
- Gain error drift: 0.4 ppm/°C typical**
- On-chip low-pass FIR filter**
- Linear phase response**
- Pass-band ripple: ±0.005 dB maximum**
- Stop-band attenuation: 100 dB minimum**
- 2.5 V supply with 1.8 V/2.5 V/3 V/3.6 V logic interface options**
- Flexible interfacing options**
- Synchronization of multiple devices**
- Daisy-chain capability**
- Power-down function**
- Temperature range: –40°C to +105°C**

APPLICATIONS

- Low power PCI/USB data acquisition systems**
- Low power wireless acquisition systems**
- Vibration analysis**
- Instrumentation**
- High precision medical acquisition**

GENERAL DESCRIPTION

The [AD7766-2-KGD](#) is a high performance, 24-bit, oversampled SAR analog-to-digital converter (ADC). The [AD7766-2-KGD](#) combines the benefits of a large dynamic range and input bandwidth, consuming 8.5 mW power.

Ideal for ultralow power data acquisition (such as PCI-based and USB-based systems), the [AD7766-2-KGD](#) provides 24-bit resolution. The combination of exceptional signal-to-noise ratio (SNR), wide dynamic range, and outstanding dc accuracy make the [AD7766-2-KGD](#) ideally suited for measuring small signal changes over a wide dynamic range. This device is particularly suitable for applications where small changes on the input are measured on larger ac or dc signals. In such an application, the [AD7766-2-KGD](#) accurately gathers both ac and dc information.

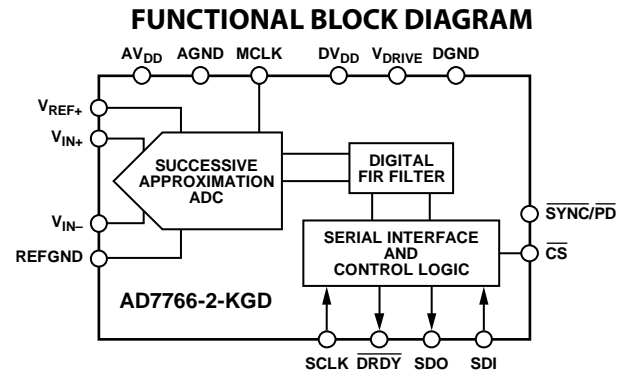


Figure 1.

The [AD7766-2-KGD](#) includes an on-board digital filter (complete with linear phase response) that acts to eliminate out-of-band noise by filtering the oversampled input voltage. The oversampled architecture also reduces front-end antialiasing requirements. Other features of the [AD7766-2-KGD](#) include a SYNC/PD (synchronization/power-down) pin that allows synchronizing of multiple [AD7766-2-KGD](#) devices or that powers down the [AD7766-2-KGD](#). The addition of an SDI pin provides the option of daisy chaining multiple [AD7766-2-KGD](#) devices.

The [AD7766-2-KGD](#) operates from a 2.5 V supply using a 5 V reference. The device operates from –40°C to +105°C.

Additional application and technical information can be found in the [AD7766-2](#) data sheet.

Known Good Die (KGD): this die is fully guaranteed to data sheet specifications.

RELATED DEVICES

Table 1. 24-Bit ADCs

| Part No. | Description |
|-------------------------------|---|
| AD7760 | 2.5 MSPS, 100 dB dynamic range, ¹ on-board differential amp and reference buffer, parallel, variable decimation |
| AD7762/AD7763 | 625 kSPS, 109 dB dynamic range, ¹ on-board differential amp and reference buffer, parallel/serial, variable decimation |
| AD7764 | 312 kSPS, 109 dB dynamic range, ¹ on-board differential amp and reference buffer, variable decimation (pin) |
| AD7765 | 156 kSPS, 112 dB dynamic range, ¹ on-board differential amp and reference buffer, variable decimation (pin) |
| AD7767 | 128 kSPS, 109.5 dB, ¹ 15 mW, 18-bit INL, serial interface |
| AD7767-1 | 64 kSPS 112.5 dB, ¹ 10.5 mW, 18-bit INL, serial interface |
| AD7767-2 | 32 kSPS, 115.5 dB, ¹ 8.5 mW, 18-bit INL, serial interface |

¹ Dynamic range at maximum output data rate.

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REVISION HISTORY

1/16—Revision 0: Initial Version

SPECIFICATIONS

$AV_{DD} = DV_{DD} = 2.5 \text{ V} \pm 5\%$, $V_{DRIVE} = 1.8 \text{ V to } 3.6 \text{ V}$, $V_{REF+} = 5 \text{ V}$, $MCLK = 1 \text{ MHz}$, common-mode input = $V_{REF+}/2$, $T_A = -40^\circ\text{C to } +105^\circ\text{C}$, unless otherwise noted.

Table 2.

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|------------------------------------|--|------------------------|---------------------------|-------------------------|-----------------------|
| OUTPUT DATA RATE (ODR) | Decimate by 32 | | | 32 | kHz |
| ANALOG INPUT | | | | | |
| Differential Input Voltage | $V_{IN+} - V_{IN-}$ | | | $\pm V_{REF+}$ | V p-p |
| Absolute Input Voltage | V_{IN+} | -0.1 | | $+V_{REF+} + 0.1$ | V |
| | V_{IN-} | -0.1 | | $+V_{REF+} + 0.1$ | V |
| Common-Mode Input Voltage | | $V_{REF+}/2 - 5\%$ | $V_{REF+}/2$ | $V_{REF+}/2 + 5\%$ | V |
| Input Capacitance | | | 22 | | pF |
| DYNAMIC PERFORMANCE | | | | | |
| Dynamic Range | Decimate by 32, ODR = 32 kHz Shorted inputs | 114 | 115.5 | | dB |
| Signal-to-Noise Ratio (SNR) | Full-scale input amplitude, 1 kHz tone | 112 | 113.5 | | dB |
| Spurious-Free Dynamic Range (SFDR) | Full-scale input amplitude, 1 kHz tone | | -128 | -116 | dB |
| Total Harmonic Distortion (THD) | Full-scale input amplitude, 1 kHz tone | | -112 | -103 | dB |
| Intermodulation Distortion (IMD) | Tone A = 11.7 kHz, Tone B = 12.3 kHz | | | | dB |
| Second-Order Terms | | | -137 | | dB |
| Third-Order Terms | | | -108 | | dB |
| DC ACCURACY | | | | | |
| Resolution | For all devices No missing codes | 24 | | | Bits |
| Differential Nonlinearity | Guaranteed monotonic to 24 bits | | | | |
| Integral Nonlinearity | 16-bit linearity | | ± 6 | ± 15 | ppm |
| Zero Error | | | 20 | | μV |
| Gain Error | | | 0.0075 | 0.075 | % FS |
| Zero Error Drift | | | 15 | | nV/ $^\circ\text{C}$ |
| Gain Error Drift | | | 0.4 | | ppm/ $^\circ\text{C}$ |
| Common-Mode Rejection Ratio | 50 Hz tone | | -110 | | dB |
| DIGITAL FILTER RESPONSE | | | | | |
| Group Delay | | | 37/ODR | | μs |
| Settling Time (Latency) | Complete settling | | 74/ODR | | μs |
| Pass-Band Ripple | | | | ± 0.005 | dB |
| Pass Band | | | $0.453 \times \text{ODR}$ | | Hz |
| -3 dB Bandwidth | | | $0.49 \times \text{ODR}$ | | Hz |
| Stop-Band Frequency | | | $0.547 \times \text{ODR}$ | | Hz |
| Stop-Band Attenuation | | 100 | | | dB |
| REFERENCE INPUT | | | | | |
| V_{REF+} Input Voltage | | 2.4 | | $2 \times AV_{DD}$ | V |
| DIGITAL INPUTS (Logic Levels) | | | | | |
| Logic Low Voltage (V_{IL}) | | -0.3 | | $+0.3 \times V_{DRIVE}$ | V |
| Logic High Voltage (V_{IH}) | | $0.7 \times V_{DRIVE}$ | | $V_{DRIVE} + 0.3$ | V |
| Input Leakage Current | | | | ± 1 | $\mu\text{A/pin}$ |
| Input Capacitance | | | 5 | | pF |
| Master Clock Rate | | | | 1.024 | MHz |
| Serial Clock Rate | | | | $1/t_8$ | Hz |
| DIGITAL OUTPUTS | | | | | |
| Data Format | Serial 24 bits, twos complement (MSB first) | | | | |
| Logic Low Voltage (V_{OL}) | Sink current ($I_{SINK} = +500 \mu\text{A}$) | | | 0.4 | V |
| Logic High Voltage (V_{OH}) | Source current ($I_{SOURCE} = -500 \mu\text{A}$) | $V_{DRIVE} - 0.3$ | | | V |

| Parameter | Test Conditions/Comments | Min | Typ | Max | Unit |
|---|---|------------------|------|-------------------------|------|
| POWER REQUIREMENTS | | | | | |
| AV _{DD} | ±5% | | 2.5 | | V |
| DV _{DD} | ±5% | | 2.5 | | V |
| V _{DRIVE} | | 1.7 | 2.5 | 3.6 | V |
| CURRENT SPECIFICATIONS | | | | | |
| Operational Current | | MCLK = 1.024 MHz | | 32 kHz output data rate | |
| Analog Quiescent Current (AI _{DD}) | | | 1.3 | 1.5 | mA |
| Digital Quiescent Current (DI _{DD}) | | | 1.37 | 1.86 | mA |
| Reference Current (I _{REF}) | | | 0.35 | 0.425 | mA |
| Static Current with MCLK Stopped | | | | | |
| AI _{DD} | | | 0.9 | 1 | mA |
| DI _{DD} | | | 1 | 93 | μA |
| Power-Down Mode Current | | | | | |
| AI _{DD} | | | 0.1 | 6 | μA |
| DI _{DD} | | | 1 | 93 | μA |
| POWER DISSIPATION | | | | | |
| Operational Power | MCLK = 1.024 MHz 32 kHz output data rate | | 8.5 | 10.5 | mW |

TIMING SPECIFICATIONS

$AV_{DD} = DV_{DD} = 2.5 \text{ V} \pm 5\%$, $V_{DRIVE} = 1.7 \text{ V}$ to 3.6 V , $V_{REF+} = 5 \text{ V}$, common-mode input = $V_{REF+}/2$, $T_A = -40^\circ\text{C}$ (T_{MIN}) to $+105^\circ\text{C}$ (T_{MAX}), unless otherwise noted. Sample tested during initial release to ensure compliance. All input signals are specified with rise time (t_R) = fall time (t_F) = 5 ns (10% to 90% of DV_{DD}) and timed from a voltage level of 1.7 V .

Table 3.

| Parameter | Limit at t_{MIN} , t_{MAX} | Unit | Description |
|---|--------------------------------|------------|--|
| DRDY OPERATION | | | |
| t_1 | 510 | ns typ | MCLK rising edge to \overline{DRDY} falling edge |
| t_2^1 | 100 | ns min | MCLK high pulse width |
| t_3^1 | 900 | ns max | MCLK low pulse width |
| t_4 | 71 | ns typ | MCLK rising edge to \overline{DRDY} rising edge |
| t_5 | 492 | ns typ | \overline{DRDY} pulse width |
| t_{READ} | $t_{\overline{DRDY}} - t_5$ | ns typ | \overline{DRDY} low period, read data during this period |
| $t_{\overline{DRDY}}$ | $32 \times t_{MCLK}$ | ns typ | \overline{DRDY} period |
| READ OPERATION | | | |
| t_6 | 0 | ns min | \overline{DRDY} falling edge to \overline{CS} setup time |
| t_7 | 6 | ns max | \overline{CS} falling edge to SDO tristate disabled |
| t_8 | 60 | ns max | Data access time after SCLK falling edge ($V_{DRIVE} = 1.7 \text{ V}$) |
| | 50 | ns max | Data access time after SCLK falling edge ($V_{DRIVE} = 2.3 \text{ V}$) |
| | 25 | ns max | Data access time after SCLK falling edge ($V_{DRIVE} = 2.7 \text{ V}$) |
| | 24 | ns max | Data access time after SCLK falling edge ($V_{DRIVE} = 3.0 \text{ V}$) |
| t_9 | 10 | ns min | SCLK falling edge to data valid hold time ($V_{DRIVE} = 3.6 \text{ V}$) |
| t_{10} | 10 | ns min | SCLK high pulse width |
| t_{11} | 10 | ns min | SCLK low pulse width |
| t_{SCLK} | $1/t_8$ | sec min | Minimum SCLK period (not shown in the timing figures) |
| t_{12} | 6 | ns max | Bus relinquish time after \overline{CS} rising edge |
| t_{13} | 0 | ns min | \overline{CS} rising edge to \overline{DRDY} rising edge |
| READ OPERATION WITH \overline{CS} LOW | | | |
| t_{14} | 0 | ns min | \overline{DRDY} falling edge to data valid setup time |
| t_{15} | 0 | ns max | \overline{DRDY} rising edge to data valid hold time |
| DAISY-CHAIN OPERATION | | | |
| t_{16} | 1 | ns min | SDI valid to SCLK falling edge setup time |
| t_{17} | 2 | ns max | SCLK falling edge to SDI valid hold time |
| SYNC/PD OPERATION | | | |
| t_{18} | 1 | ns typ | $\overline{SYNC/PD}$ falling edge to MCLK rising edge |
| t_{19} | 20 | ns typ | MCLK rising edge to \overline{DRDY} rising edge going into $\overline{SYNC/PD}$ mode |
| t_{20} | 1 | ns min | $\overline{SYNC/PD}$ rising edge to MCLK rising edge |
| t_{21} | 510 | ns typ | MCLK rising edge to \overline{DRDY} falling edge coming out of $\overline{SYNC/PD}$ mode |
| $t_{SETTLING}$ | 2357 | t_{MCLK} | Filter settling time (in MCLK periods) after a reset or power-down |

¹ t_2 and t_3 allow a ~90% to 10% duty cycle to be used for the MCLK input, where the minimum is 10% for the clock high time and 90% for MCLK low time. The maximum MCLK frequency is 1.024 MHz.

Timing Diagrams

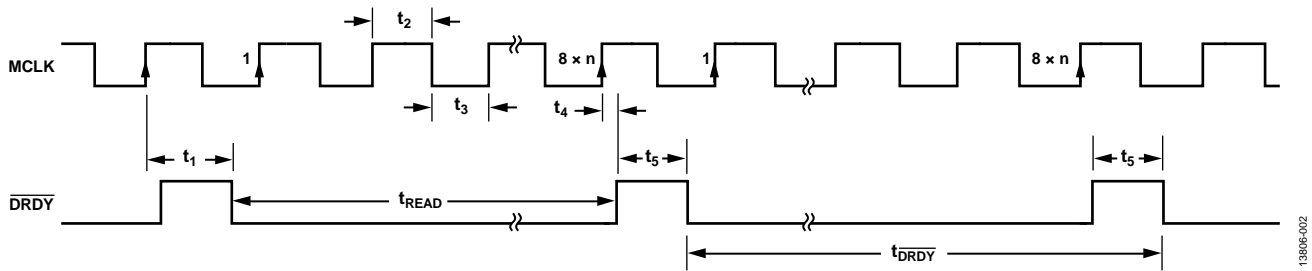


Figure 2. \overline{DRDY} vs. MCLK Timing Diagram, $n = 4$ (Decimate by 32)

13806-002

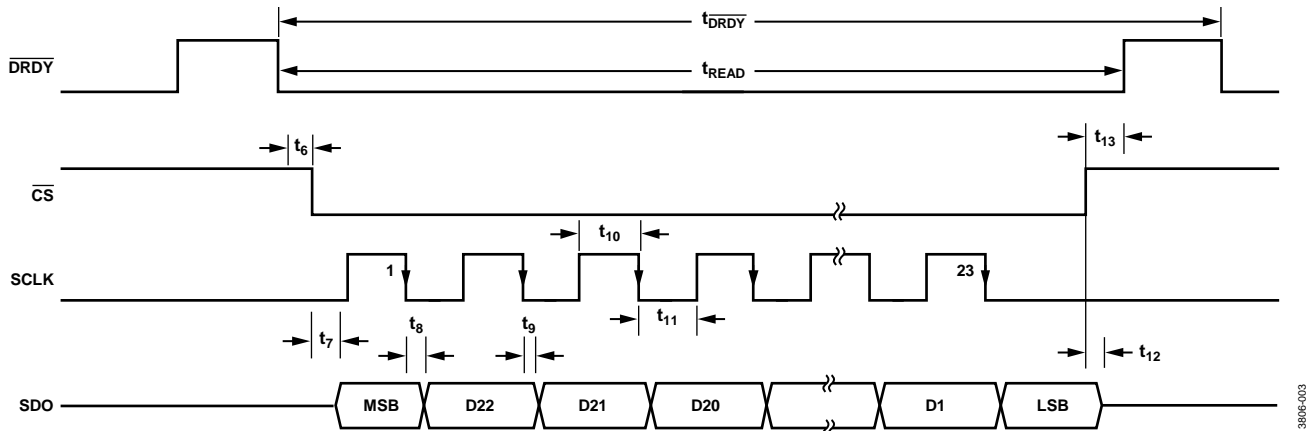


Figure 3. Serial Timing Diagram, Reading Data Using \overline{CS}

13806-003

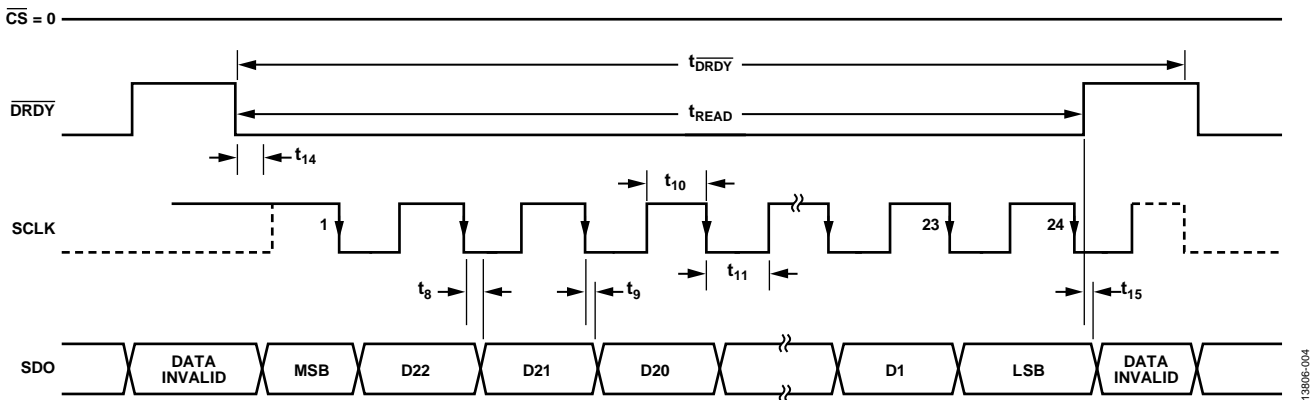


Figure 4. Serial Timing Diagram, Reading Data Setting \overline{CS} Logic Low

13806-004

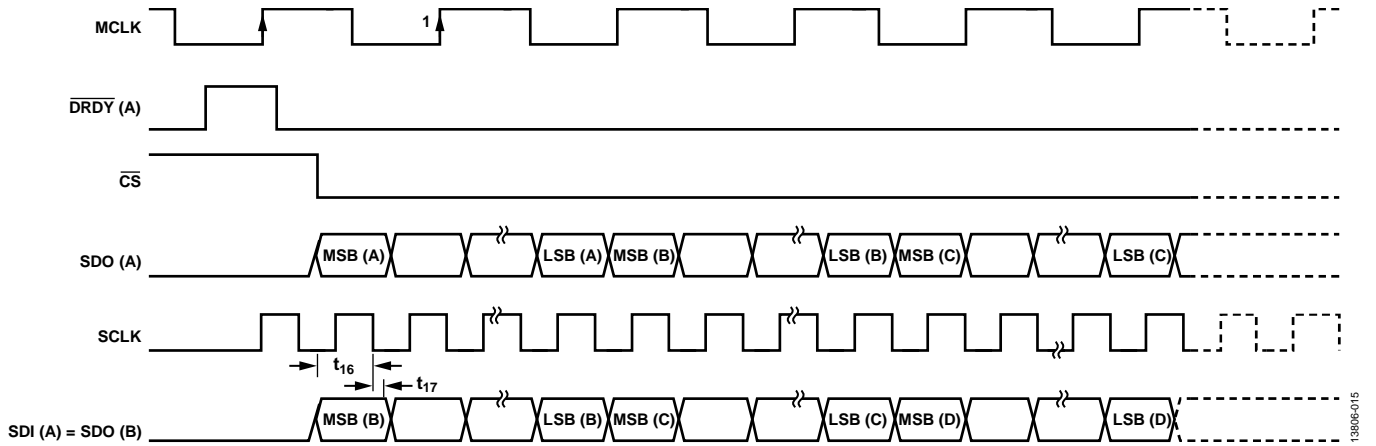


Figure 5. Daisy-Chain SDI Setup and Hold Timing

13806-015

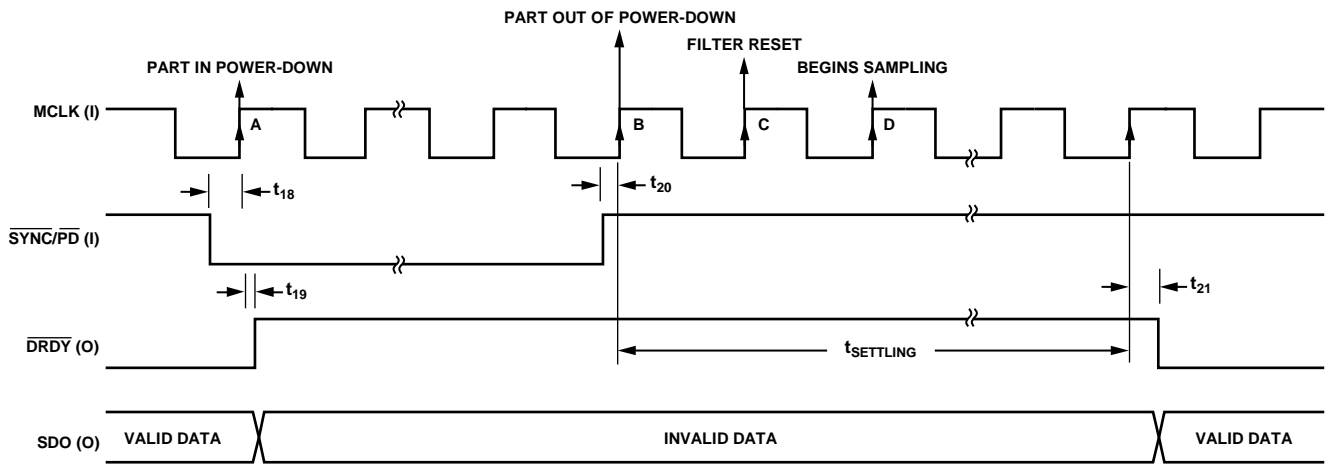


Figure 6. Reset, Synchronization, and Power-Down Timing

13806-005

ABSOLUTE MAXIMUM RATINGS

Table 4.

| Parameter | Rating |
|---|-------------------------------|
| AV_{DD} to AGND | -0.3 V to +3 V |
| DV_{DD} to DGND | -0.3 V to +3 V |
| AV_{DD} to DV_{DD} | -0.3 V to +0.3 V |
| V_{REF+} to REFGND | -0.3 V to +7 V |
| REFGND to AGND | -0.3 V to +0.3 V |
| V_{DRIVE} to DGND | -0.3 V to +6 V |
| V_{IN+} , V_{IN-} to AGND | -0.3 V to $V_{REF+} + 0.3$ V |
| Digital Inputs to DGND | -0.3 V to $V_{DRIVE} + 0.3$ V |
| Digital Outputs to DGND | -0.3 V to $V_{DRIVE} + 0.3$ V |
| AGND to DGND | -0.3 V to +0.3 V |
| Input Current to Any Pin Except Supplies ¹ | ±10 mA |
| Operating Temperature Range | -40°C to +105°C |
| Storage Temperature Range | -65°C to +150°C |
| Junction Temperature | 150°C |
| Electrostatic Discharge (ESD) | 1 kV |

¹ Transient currents of up to 100 mA do not cause SCR latch-up.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATION AND FUNCTION DESCRIPTIONS

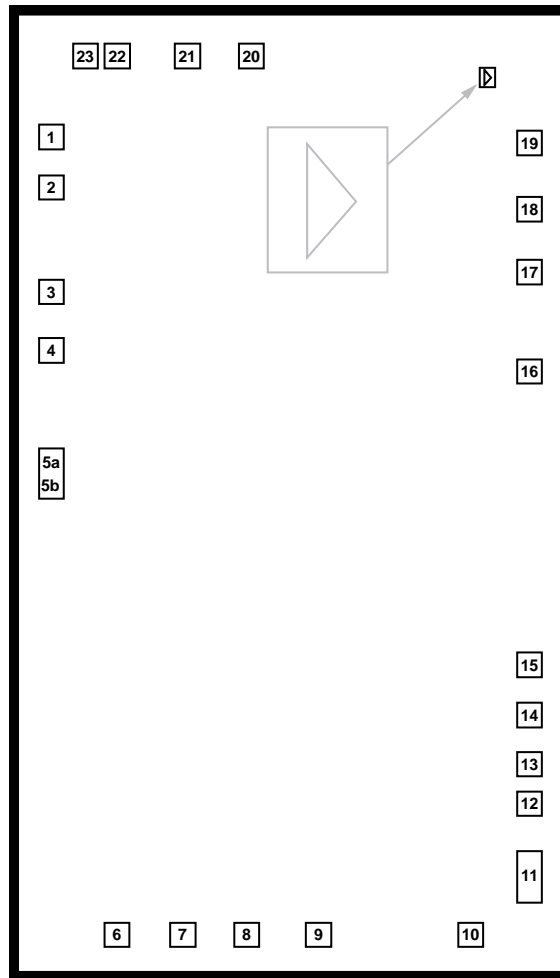


Figure 7. Pad Configuration

Table 5. Pad Function Descriptions

| Pad No. | X-Axis (μm) | Y-Axis (μm) | Mnemonic | Pad Type | Description |
|---------|--------------------------|--------------------------|---|----------|--|
| 1 | -773 | +1064 | REFGND | Single | Reference Ground. Ground connection for the reference voltage. Decouple the input reference voltage ($V_{\text{REF}+}$) to this pin. |
| 2 | -773 | +916 | REFGND | Single | Reference Ground. Ground connection for the reference voltage. Decouple the input reference voltage ($V_{\text{REF}+}$) to this pin. |
| 3 | -773 | +600 | $V_{\text{IN}+}$ | Single | Positive Input of the Differential Analog Input. |
| 4 | -773 | +426 | $V_{\text{IN}-}$ | Single | Negative Input of the Differential Analog Input. |
| 5a | -773 | +93 | AGND | Double | Power Supply Ground for Analog Circuitry. |
| 5b | -773 | +18 | AGND | Double | Power Supply Ground for Analog Circuitry. |
| 6 | -561 | -1326 | $\overline{\text{SYNC}}/\overline{\text{PD}}$ | Single | Synchronization ($\overline{\text{SYNC}}$) Pin. The $\overline{\text{SYNC}}$ pin can synchronize multiple AD7766-2-KGD devices. Power-Down Input Pin ($\overline{\text{PD}}$). The $\overline{\text{PD}}$ pin puts the AD7766-2-KGD device into power-down mode |

| Pad No. | X-Axis (μm) | Y-Axis (μm) | Mnemonic | Pad Type | Description |
|---------|--------------------------|--------------------------|--------------------------|----------|---|
| 7 | -353 | -1319 | DV _{DD} | Single | Digital Power Supply Input, 2.5 V. In cases where a logic voltage of 2.5 V for interfacing is used (2.5 V applied to V _{DRIVE} pin), the DV _{DD} and V _{DRIVE} pins can be connected to the same voltage supply rail. |
| 8 | -141 | -1317 | DV _{DD} | Single | Digital Power Supply Input, 2.5 V. In cases where a logic voltage of 2.5 V for interfacing is used (2.5 V applied to V _{DRIVE} pin), the DV _{DD} and V _{DRIVE} pins can be connected to the same voltage supply rail. |
| 9 | +105 | -1340 | V _{DRIVE} | Single | Logic Power Supply Input, 1.8 V to 3.6 V. The voltage supplied at this pin determines the operating voltage of the digital logic interface. |
| 10 | +601 | -1336 | V _{DRIVE} | Single | Logic Power Supply Input, 1.8 V to 3.6 V. The voltage supplied at this pin determines the operating voltage of the digital logic interface. |
| 11 | +799 | -1161 | SDO | Double | Serial Data Output. The conversion result from the AD7766-2-KGD is output on the SDO pin as a 24-bit, twos complement, MSB first, serial data stream. |
| 12 | +784 | -944 | DGND | Single | Digital Logic Power Supply Ground. |
| 13 | +784 | -826 | DGND | Single | Digital Logic Power Supply Ground. |
| 14 | +784 | -677 | DGND | Single | Digital Logic Power Supply Ground. |
| 15 | +800 | -517 | $\overline{\text{DRDY}}$ | Single | Data Ready Output. A falling edge on the $\overline{\text{DRDY}}$ signal indicates that a new conversion data result is available in the output register of the AD7766-2-KGD. |
| 16 | +800 | +363 | SCLK | Single | Serial Clock Input. The SCLK input provides the serial clock for all serial data transfers with AD7766-2-KGD devices. |
| 17 | +800 | +663 | MCLK | Single | Master Clock Input. The sampling frequency of the AD7766-2-KGD is equal to the MCLK frequency. |
| 18 | +800 | +850 | SDI | Single | Serial Data Input. This pin is the daisy-chain input of the AD7766-2-KGD. |
| 19 | +800 | +1051 | $\overline{\text{CS}}$ | Single | Chip Select Input. The $\overline{\text{CS}}$ input selects a specific AD7766-2-KGD device and acts as an enable on the SDO pin. In cases where $\overline{\text{CS}}$ is used, the MSB of the conversion result is clocked onto the SDO line on the $\overline{\text{CS}}$ falling edge. The $\overline{\text{CS}}$ input allows multiple AD7766-2-KGD devices to share the same SDO line. This function allows the user to select the appropriate device by supplying it with a logic low $\overline{\text{CS}}$ signal, which enables the SDO pin of the concerned device. |
| 20 | -125 | +1319 | AV _{DD} | Single | Analog Power Supply, 2.5 V. |
| 21 | -333 | +1319 | AV _{DD} | Single | Analog Power Supply, 2.5 V. |
| 22 | -561 | +1317 | V _{REF+} | Single | Reference Input for the AD7766-2-KGD. Apply an external reference to this input pin. The V _{REF+} input ranges from 2.4 V to 5 V. The reference voltage input is independent of the voltage magnitude applied to the AV _{DD} pin. |
| 23 | -667 | +1317 | V _{REF+} | Single | Reference Input for the AD7766-2-KGD. Apply an external reference to this input pin. The V _{REF+} input ranges from 2.4 V to 5 V. The reference voltage input is independent of the voltage magnitude applied to the AV _{DD} pin. |

OUTLINE DIMENSIONS

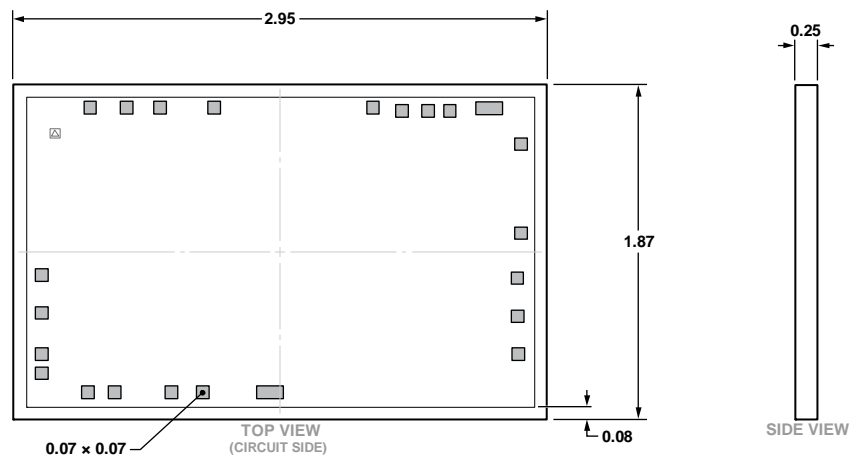


Figure 8. 23-Pad Bare Die [CHIP]
(C-23-1)
Dimensions shown in millimeters

11-03-2015-A

DIE SPECIFICATIONS AND ASSEMBLY RECOMMENDATIONS

Table 6. Die Specifications

| Parameter | Value | Unit |
|----------------------|---------------------|----------------|
| Chip Size | 2870 (x) × 1790 (y) | μm |
| Scribe Line Width | 80 (x) × 80 (y) | μm |
| Die Size | 2950 (x) × 1870 (y) | μm |
| Thickness | 305 | μm |
| Backside | Bare silicon | Not applicable |
| Passivation | Nitride | Not applicable |
| Bond Pads (Minimum) | 70 × 70 | μm |
| Bond Pad Composition | AlCu (0.5%) | % |
| ESD | 1 | kV |

Table 7. Assembly Recommendations

| Assembly Component | Recommendation |
|--------------------|-----------------------------|
| Die Attach | No special recommendations |
| Bonding Method | Gold ball or aluminum wedge |
| Bonding Sequence | Pad 1 and Pad 2 first |

ORDERING GUIDE

| Model | Temperature Range | Package Description | Package Option |
|-----------------|-------------------|-------------------------------------|----------------|
| AD7766-2-KGD-WP | -40°C to +105°C | 23-Pad Bare Die [CHIP], Waffle Pack | C-23-1 |